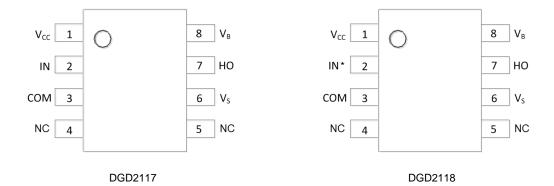


Pin Diagrams

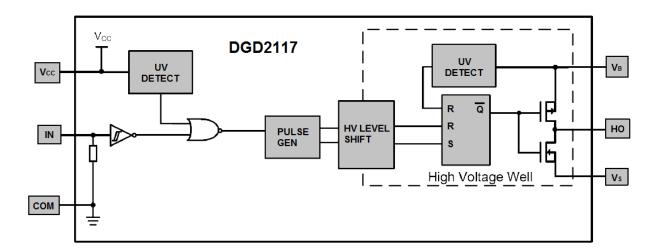


Top View SO-8

Pin Descriptions

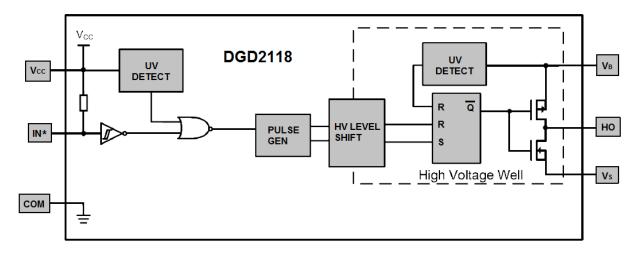
Pin Number	Pin Name	Function
1	Vcc	Logic and gate driver supply
2	IN	DGD2117 Logic input for gate driver output (HO), in phase with HO
2	IN*	DGD2118 Logic input for gate driver output (HO), out of phase with HO
3	COM	Logic ground
4, 5	NC	No Connection (No Internal Connection)
6	Vs	High-side floating supply return
7	НО	High-side gate drive output
8	V _B	High-side floating supply

Functional Block Diagram





Functional Block Diagram (continued)



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	VB	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	Vно	Vs-0.3 to V _B +0.3	V
Logic Supply Voltage	Vcc	-0.3 to +24	V
Logic Input Voltage	Vin	-0.3 to Vcc+0.3	V
Allowable Offset Supply Voltage Transient	dVs / dt	50	V/ns

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P _D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	200	°C/W
Thermal Resistance, Junction to Case (Note 6)	Rejc	45	°C/W
Operating Temperature	TJ	+150	
Lead Temperature (Soldering, 10s)	T∟	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V _B	V _S + 10	V _S + 20	V
High Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High Side Floating Output Voltage	Vно	Vs	VB	V
Low Side and Logic Fixed Supply Voltage	Vcc	10	20	V
Logic Input Voltage	Vin	0	Vcc	V
Ambient Temperature	TA	-40	+125	°C

Note: 6. Logic operation for $V_S = -5V$ to +600V.



DC Electrical Characteristics (VBIAS (VCC, VBS) = 15V, @TA = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
Logic "1" (DGD2117) & Logic "0" (DGD2118) Input Voltage (Note 8)		ViH	9.5	ı	ı	>	_
Logic "0" (DGD2117) & Logic "1" (DGD: Voltage (Note 8)	2118) Input	VIL		1	6.0	٧	_
High Level Output Voltage, VBIAS - VO		Vон		0.05	0.2	V	$I_0 = 2mA$
Low Level Output Voltage, Vo		Vol		0.02	0.1	V	$I_0 = 2mA$
Offset Supply Leakage Current		ILK		_	50	μΑ	$V_B = V_S = 600V$
Quiescent V _{BS} Supply Current		I _{BSQ}		50	240	μΑ	V _{IN} = 0V or V _{CC}
Quiescent Vcc Supply Current		Iccq		70	340	μΑ	VIN = 0V or VCC
Logic "1" Input Bias Current	DGD2117 DGD2118	I _{IN+}	_	20	40	μΑ	VIN = VCC VIN = 0V
Logic "0" Input Bias Current	DGD2117 DGD2118	I _{IN} -	_	_	5.0	μΑ	VIN = 0V VIN = VCC
V _{BS} Supply Under-Voltage Positive Goi	ng Threshold	V _{BSUV+}	7.6	8.6	9.6	V	_
V _{BS} Supply Under-Voltage Negative Go	oing Threshold	V _{BSUV} -	7.2	8.2	9.2	V	_
Vcc Supply Under-Voltage Positive Go	ing Threshold	Vccuv+	7.6	8.6	9.6	V	_
Vcc Supply Under-Voltage Negative Go	Vccuv-	7.2	8.2	9.2	V	_	
Output High Short Circuit Pulsed Curre	lo+	200	290		mA	Vo = 0V, V _{IN} = Logic "1", PW ≤ 10µs	
Output Low Short Circuit Pulsed Currer	lo-	420	600	_	mA	V _O = 15V, V _{IN} = Logic "0", PW ≤ 10µs	

Notes:

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-On Propagation Delay	toN	_	125	200	ns	$V_S = 0V$
Turn-Off Propagation Delay	toff	_	105	180	ns	Vs = 600V
Turn-On Rise Time	t _r	_	75	130	ns	_
Turn-Off Fall Time	t _f	_	35	65	ns	_

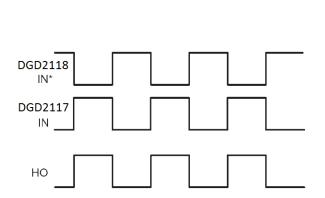
^{7.} The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the logic input pins: IN and IN*. The V_O and I_O parameters are referenced to

COM and are applicable to the output pin: HO.

8. For optimal operation, it is recommended that the input pulses (IN and IN*) should have a minimum amplitude of 9.5V with a minimum pulse width of 250ns.



Timing Waveforms





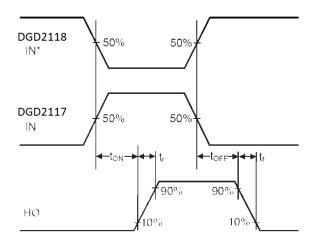


Figure 2. Switching Time Waveform Definitions

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Typical Performance Characteristics (Vcc = 15V, @TA = +25°C, unless otherwise specified.)

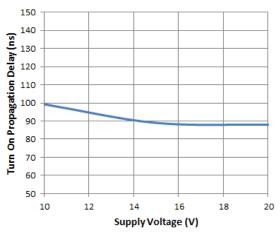


Figure 3. Turn-on Propagation Delay vs. Supply Voltage

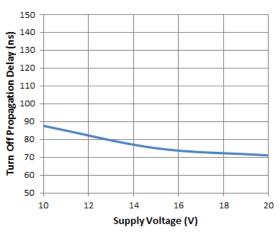


Figure 5. Turn-off Propagation Delay vs. Supply Voltage

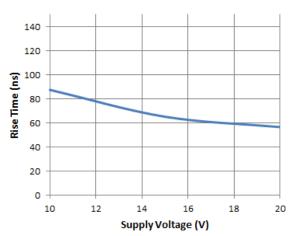


Figure 7. Rise Time vs. Supply Voltage

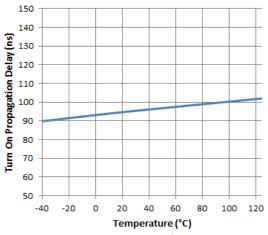


Figure 4. Turn-on Propagation Delay vs. Temperature

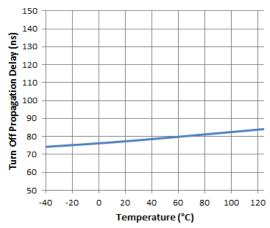


Figure 6. Turn-off Propagation Delay vs. Temperature

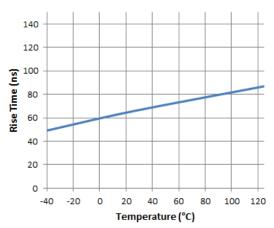


Figure 8. Rise Time vs. Temperature



Typical Performance Characteristics (continued)

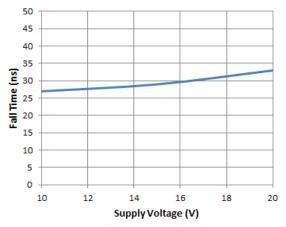


Figure 9. Fall Time vs. Supply Voltage

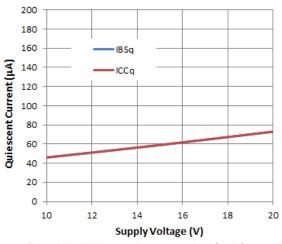


Figure 11. Quiescent Current vs. Supply Voltage

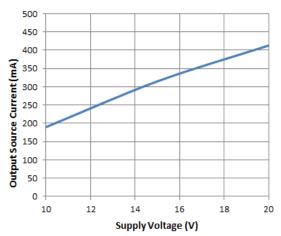


Figure 13. Output Source Current vs. Supply Voltage

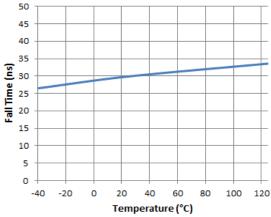


Figure 10. Fall Time vs. Temperature

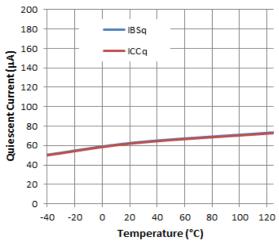


Figure 12. Quiescent Current vs. Temperature

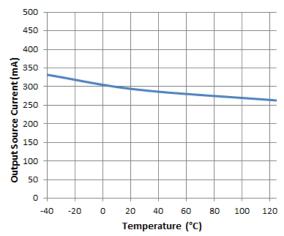


Figure 14. Output Source Current vs. Temperature



Typical Performance Characteristics (continued)

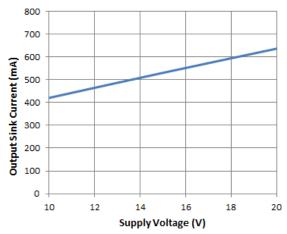


Figure 15. Output Sink Current vs. Supply Voltage

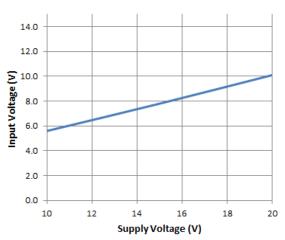


Figure 17. DGD2117 Logic 1 (DGD2118 Logic 0) Input Voltage vs. Supply Voltage

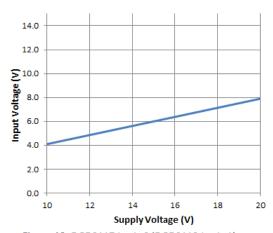


Figure 19. DGD2117 Logic 0 (DGD2118 Logic 1)
Input Voltage vs. Supply Voltage

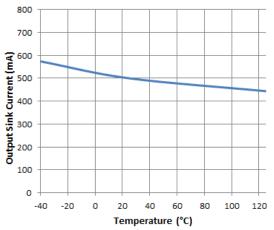


Figure 16. Output Sink Current vs. Temperature

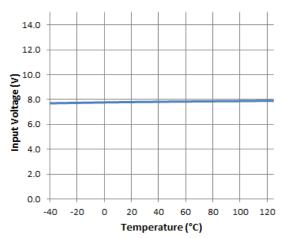


Figure 18. DGD2117 Logic 1 (DGD2118 Logic 0) Input Voltage vs. Temperature

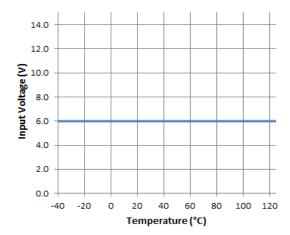


Figure 20. DGD2117 Logic 0 (DGD2118 Logic 1) Input Voltage vs. Temperature



Typical Performance Characteristics (continued)

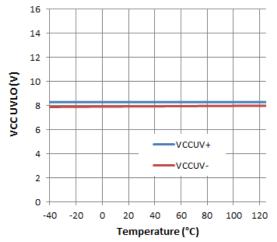
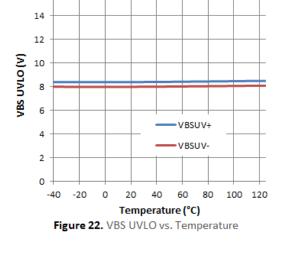


Figure 21. VCC UVLO vs. Temperature



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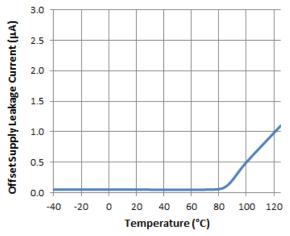


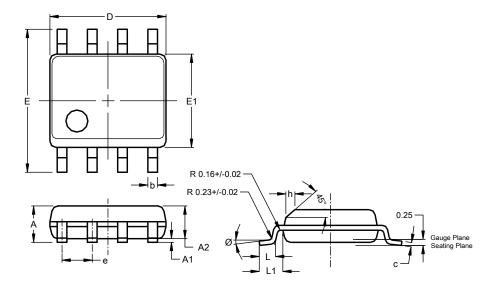
Figure 23. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

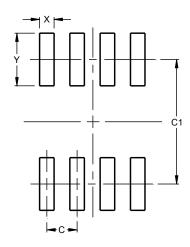


,	SO-8 (Type TH)						
Dim	Min	Max	Тур				
Α	1.35	1.75					
A1	0.10	0.25					
A2			1.45				
b	0.35	0.51					
С	0.190	0.248					
D	4.80	5.00	4.90				
Е	5.80	6.20	6.00				
E1	3.80	4.00	3.90				
е			1.27				
h	0.25	0.50					
L	0.41	1.27					
L1			1.04				
Ø	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
O	1.27
C1	5.20
Х	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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